

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
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Total Attachments: 2	
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**DECLARATION AND ASSIGNMENT
FOR PATENT AND DESIGN APPLICATIONS**

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

Title of Invention ⇒ **BIASING VOLTAGE GENERATING CIRCUIT FOR AVALANCHE
PHOTODIODE AND RELATED CONTROL CIRCUIT**

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that

Application not Attached ⇒ This declaration is directed to the application attached hereto. If the application is not attached hereto, the application is as identified by the attorney docket number as set forth above and/or the following:

Enter Appln. No. ⇒ **United States Application Number or PCT International Appln. No.**

Enter Filing Date ⇒ **filed on**

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

Insert Name of Assignee ⇒ **WHEREAS, Realtek Semiconductor Corp.**

Insert Address of Assignee ⇒ **of No.2 Innovation Road II, Science Park, Hsinchu 300, Taiwan (R.O.C.)**

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

Check Box if Appropriate ⇒ **in any foreign countries.**

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned has sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries; and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

